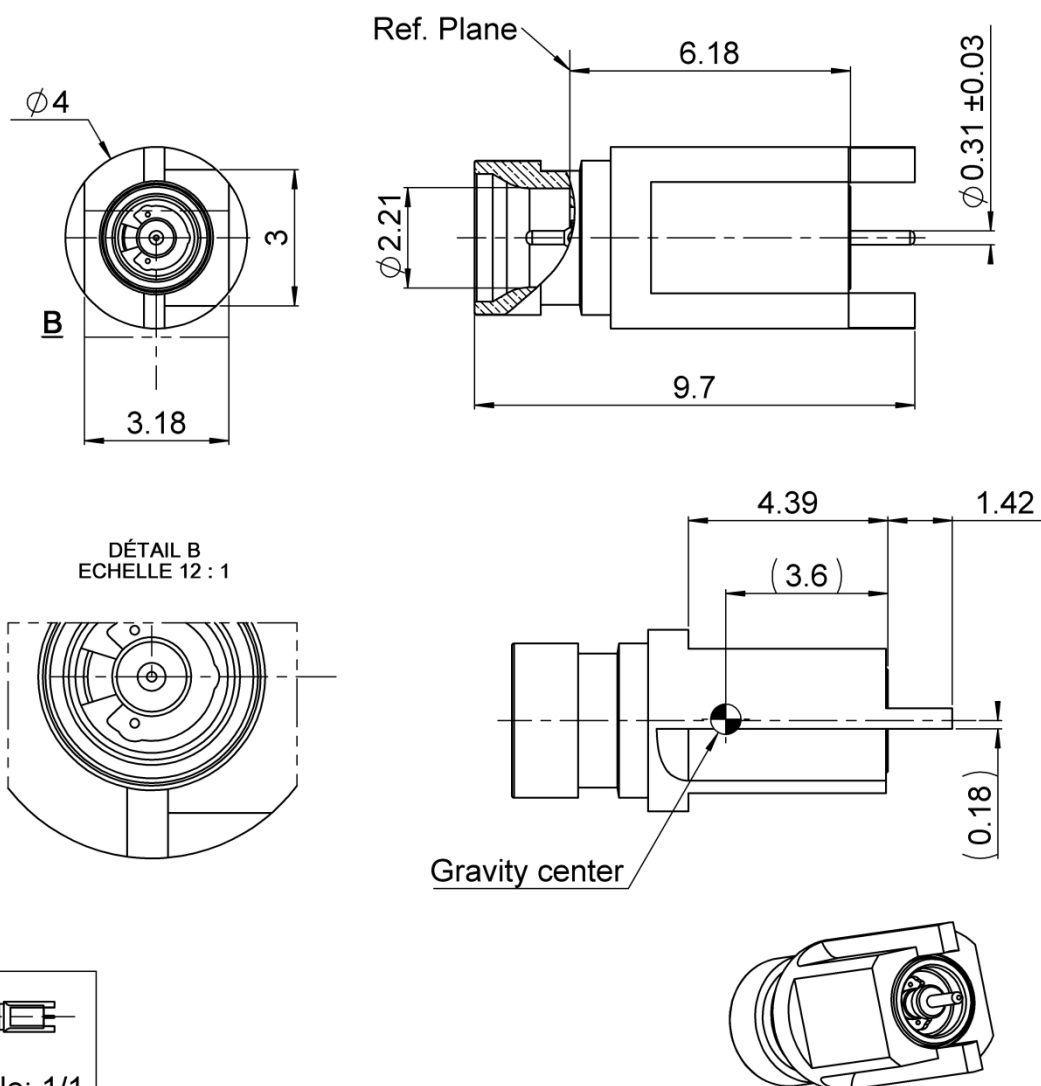


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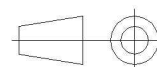
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All dimensions are in mm. Tolerances according ISO 2768 m-H



COMPONENTS	MATERIALS	PLATING (μm)
Body	BERYLLIUM COPPER; BRASS	N2PGR
Center contact	BERYLLIUM COPPER	N2PGR
Outer contact		
Insulator	PEEK	
Gasket		
Others parts		
-	-	-
-	-	-

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PACKAGING

Standard	Unit	Other
500	Contact us	Contact us

ELECTRICAL CHARACTERISTICS

Impedance	50	Ω
Frequency	0-65	GHz
VSWR	* + 0,000	x F(GHz) Maxi
Insertion loss	*0.02+0.012	\sqrt{F} (GHz) dB Maxi
RF leakage	- (NA	- F(GHz)) dB Maxi
Voltage rating	125	Veff Maxi
Dielectric withstanding voltage	250	Veff mini
Insulation resistance	5000	M Ω mini

MECHANICAL CHARACTERISTICS

Center contact retention		
Axial force – Mating End	6.7	N mini
Axial force – Opposite end	6.7	N mini
Torque	NA	N.cm mini

Recommended torque		
Mating	NA	N.cm
Panel nut	NA	N.cm

Mating life	50	Cycles mini
Nominal Weight (Add +15% for max weight)	0,512	g

ENVIRONMENTAL

Operating temperature	-65/+165	°C
Hermetic seal	NA	Atm.cm3/s
Panel leakage	NA	

SPECIFICATION

RAD-GEN-CONN-006

OTHER CHARACTERISTICS

Assembly instruction:

Others:

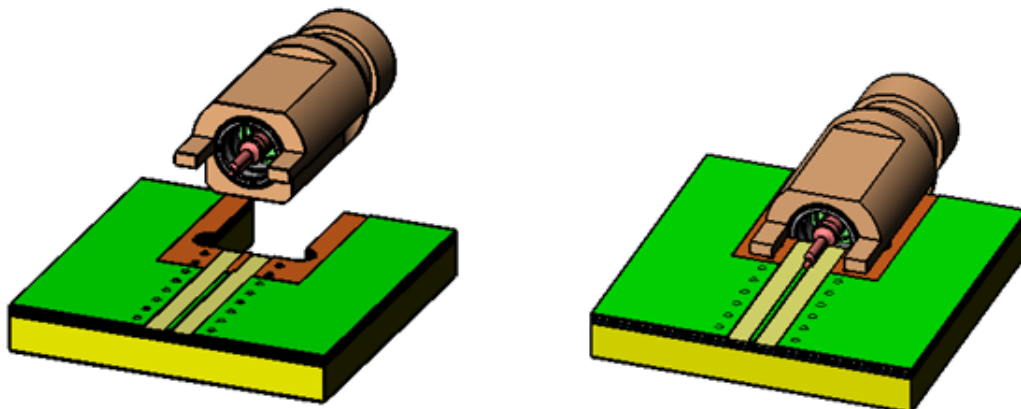
- * **1.15 (DC-26.5 GHz) 1.35 (26.5-40 GHz)**
- * **Coaxial transmission line only**
- * **RF performances highly depend on PCB adaptation**

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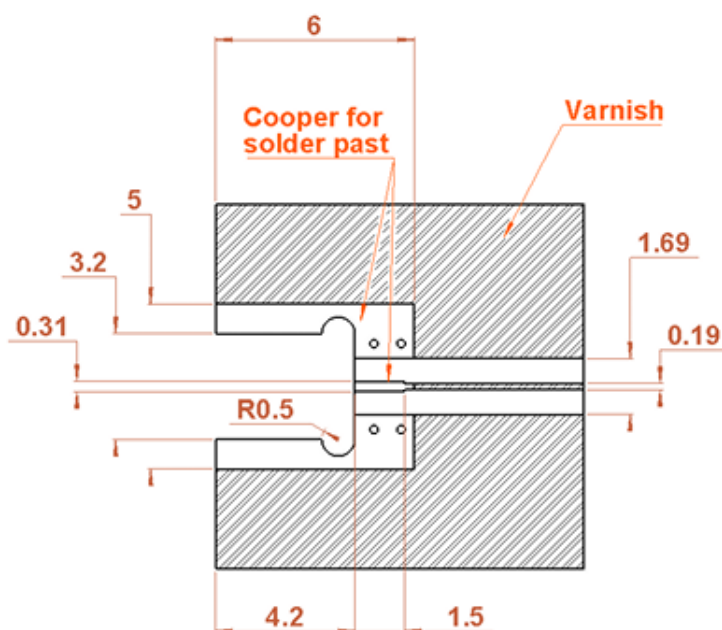
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PCB (nominal dimensions)



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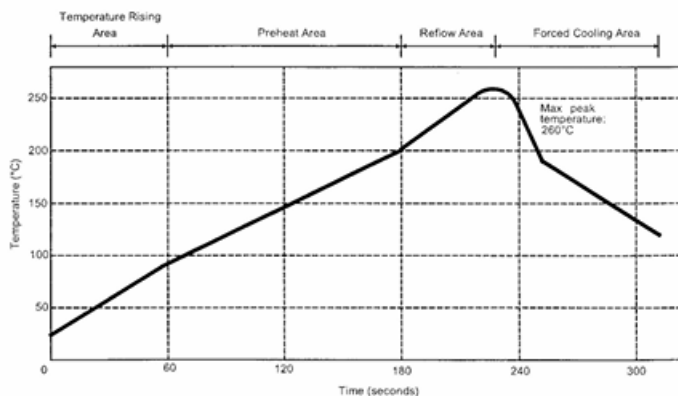
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SOLDER PROCEDURE

1. Deposit solder paste 'SnAg4Cu0.5' on mounting zone by screen printing application.
We recommend a low residue flux.
We advise a thickness of 150 µm (5.850 microinch). Verify that the edges of the zone are clean.
2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component .
Adhesive agents must not be used on the receptacle.
3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
4. The cleaning of printed circuit boards is not obliged .

Verification of solder joints and position of the component by visual inspection.



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to -4	°C/sec
Max dwell time above 100°C	420	sec

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PACKAGING

